

**●USP-10B(DAF) Power Dissipation**

Power dissipation data for the USP-10B is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: For a 4-layer PCB measuring 76.2mm  
×114.3mm (approximately 8700mm<sup>2</sup> on one side)

The copper foil areas are as follows.

1st layer: No copper foil (For signal layer)

2nd layer: 74.2mm x 74.2mm (Connected to heat sink)

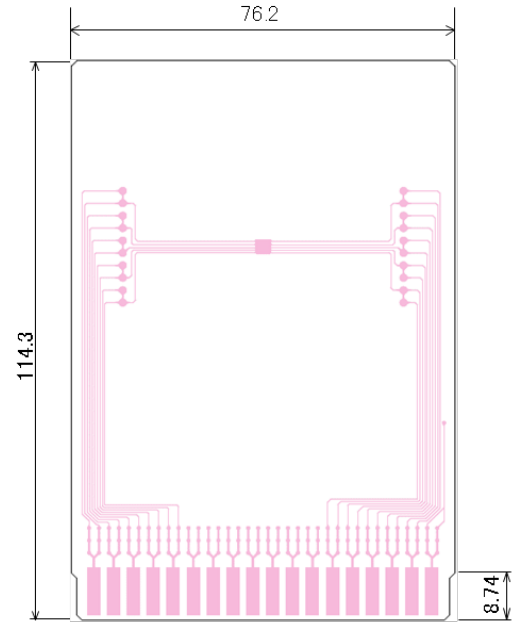
3rd layer: 74.2mm x 74.2mm (not connected to heat sink)

4th layer: No copper foil (For signal layer)

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: φ0.3mm

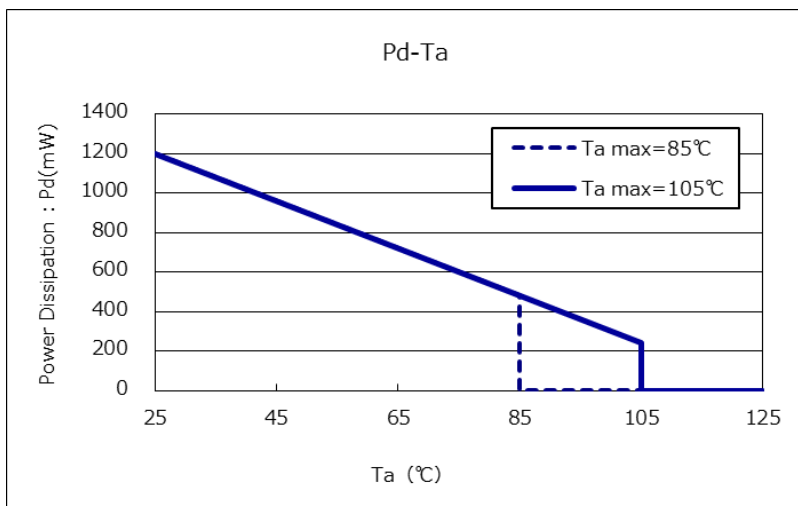


Evaluation Board Layout (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ( T<sub>imax</sub>=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	T <sub>a</sub> max=125°C	T <sub>a</sub> max=150°C	
25	1200	1200	83.33
85	480	480	
105	0	240	
125	0	0	



**●USP-10B(DAF) Power Dissipation ※Tjmax=150°C**

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1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: For a 4-layer PCB measuring 76.2mm x 114.3mm (approximately 8700mm<sup>2</sup> on one side)

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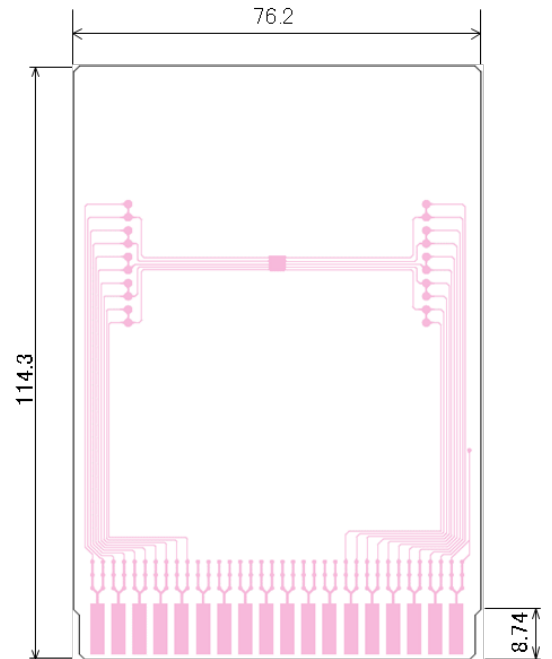
3rd layer: 74.2mm x 74.2mm (not connected to heat sink)

4th layer: No copper foil (For signal layer)

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: φ0.3mm



Evaluation Board Layout (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ( Tjmax=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	Ta max=125°C	Ta max=150°C	
25	1500	1500	83.33
125	300	300	
150	0	0	

